



Material Content Data Sheet



Sales Product Name		ICE2QR0665Z		Issued		24. January 2018		
MA#		MA001616108						
Package		PG-DIP-7-3		Weight*		644.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.769	0.27	0.27	2745	2745
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6008	
wire	non noble metal	copper	7440-50-8	157.218	24.40	25.04	243961	250344
	noble metal	gold	7440-57-5	0.369	0.06	0.06	573	573
	encapsulation	organic material	carbon black	1333-86-4	2.359	0.37		3660
encapsulation	plastics	epoxy resin	-	63.688	9.88		98827	
	inorganic material	silicondioxide	60676-86-0	405.713	62.95	73.20	629563	732050
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10024	10024
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2474	2474
glue	plastics	epoxy resin	-	0.202	0.03		313	
	noble metal	silver	7440-22-4	0.952	0.15	0.18	1477	1790
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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